2SB1548A

Silicon PNP epitaxial planar type

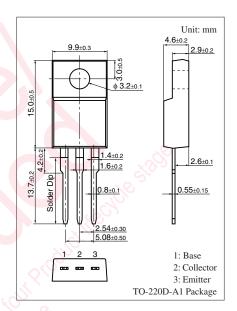
For power amplification Complementary to 2SD2374A

■ Features

- High forward current transfer ratio h_{FE} which has satisfactory linearity
- Low collector-emitter saturation voltage V_{CE(sat)}
- Full-pack package which can be installed to the heat sink with one screw

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	-80	V
Collector-emitter voltage (Base open)	V _{CEO}	-80	V
Emitter-base voltage (Collector open)	V_{EBO}	-5	V
Collector current	I_{C}	-3	A
Peak collector current	I _{CP}	-5	A
Collector power $T_C = 25^{\circ}C$	P _C	25	W
dissipation		2	40/10
Junction temperature	T_{j}	150	S °C
Storage temperature	T_{stg}	-55 to +150	°C
			VI In



■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = -30 \text{ mA}, I_B = 0$	-80			V
Base-emitter voltage	V_{BE}	$V_{CE} = -4 \text{ V}, I_{C} = -3 \text{ A}$			-1.8	V
Collector-emitter cutoff current (E-B short)	I _{CES}	$V_{CE} = -80 \text{ V}, V_{BE} = 0$			-200	μΑ
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = -60 \text{ V}, I_B = 0$			-300	μΑ
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = -5 \text{ V}, I_C = 0$			-1	mA
Forward current transfer ratio	h _{FE1} *	$V_{CE} = -4 \text{ V}, I_{C} = -1 \text{ A}$	70		250	_
	h _{FE2}	$V_{CE} = -4 \text{ V}, I_C = -3 \text{ A}$	10			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = -3 \text{ A}, I_B = -0.375 \text{ A}$			-1.2	V
Transition frequency	f_T	$V_{CE} = -10 \text{ V}, I_{C} = -0.5 \text{ A}, f = 10 \text{ MHz}$		30		MHz
Turn-on time	t _{on}	$I_C = -1 A, I_{B1} = -0.1 A, I_{B2} = 0.1 A$		0.5		μs
Storage time	t _{stg}	$V_{CC} = -50 \text{ V}$		1.2		μs
Fall time	t _f			0.3		μs

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	Q	Р
h _{FE1}	70 to 150	120 to 250

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Collector power dissipation P_C (W)

 $P_C - T_a$

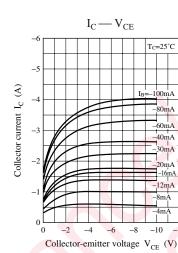
(2)Without heat sink (Pc=2W)

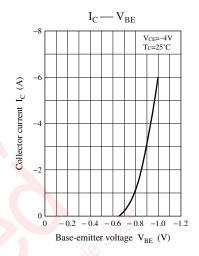
120

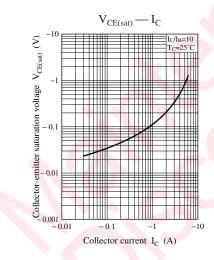
Ambient temperature T_a (°C)

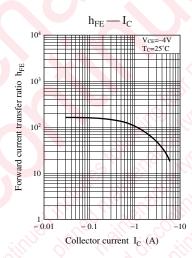
160

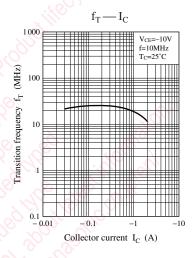
(1)T_C=Ta

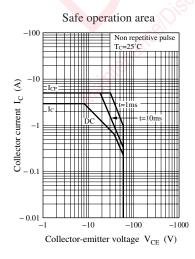


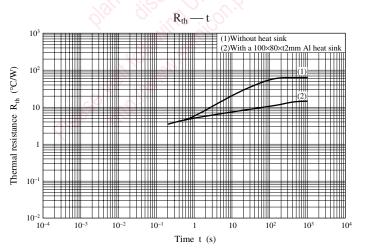












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